ABSOCIATION CONNECTING LECTRONICS INDUSTRIES® INTERNATIONAL AND A	. IPC, Bannock	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declar he declaratio	ration of the an encompass	substances es all lower	within the r level mat	manufacture erials for wh	er listed ite hich the ma	m. Note: nufacture	if the item is an as er has engineering	sembly with lowe responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distri				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	als and Mfg Information				
Supplier Information															
Company name*	Company unique ID			Unique ID Authority					Response Date*						
onsemi											2024-05-20				
Contact Name	Title - Conta	Title - Contact			Phone - Contact*					Email - Contact*					
Product-Env-Stewards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
Authorized Representative*	Title - Representative			Phone - Representative*				Email - Representative*							
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com						
Requester Item Number	Mfr Iten	n Number	Number Mfr Item Name			Effective Da	ate Version	n N	Manufacturing Site		W	'eight*	UOM	Unit Type	
	NC7SZ	75L6X	Single D-Type F/F			2024-05-20		1	ТНВ		2.	09	mg	Each	
Manufacturing Proccess Inforn	ation						L								
Terminal Plating / Grid Array	Array Material Terminal B		Alloy	J-STD-020 MSL Rating		Peak Process Body Tem		Femperatur	erature Max Time at Peak		Temperature Number of Reflow C		ber of Reflow Cyc	les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 1		1		260		C	30		second	s 3			
Comments								·							
evel 1 - maximum time at peak temper	ature during so	ldering is 10-3	0 seconds												
or more information regarding mater	al composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.04	mg	Supplier	Silicon (Si)	7440-21-3		0.04	mg
Die Attach Tape	0.003	mg	Supplier	Oxirane, (chloromethyl)-, homopolymer	24969-06-0		0.0005	mg
			Supplier	2-Propenoic acid, 2-methyl-, polymer with butyl 2-propenoate and methyl 2- methyl-2-propenoate	25035-69-2		0.0005	mg
			Supplier	Proprietary	Proprietary Data		0.0003	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0013	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0005	mg
Lead Frame	0.803	mg	Supplier	Magnesium (Mg)	7439-95-4		0.001	mg
			Supplier	Silicon (Si)	7440-21-3		0.0063	mg
			В	Nickel (Ni)	7440-02-0		0.0261	mg
			Supplier	Copper (Cu)	7440-50-8		0.7696	mg
Mold Compound-Black	1.207	mg		Epoxy resin	proprietary data		0.0604	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0278	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.0604	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0048	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0278	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.026	mg
Plating	0.025	mg	Supplier	Silver (Ag)	7440-22-4		0.0001	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			В	Nickel (Ni)	7440-02-0		0.0247	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond	0.012	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0117	mg